

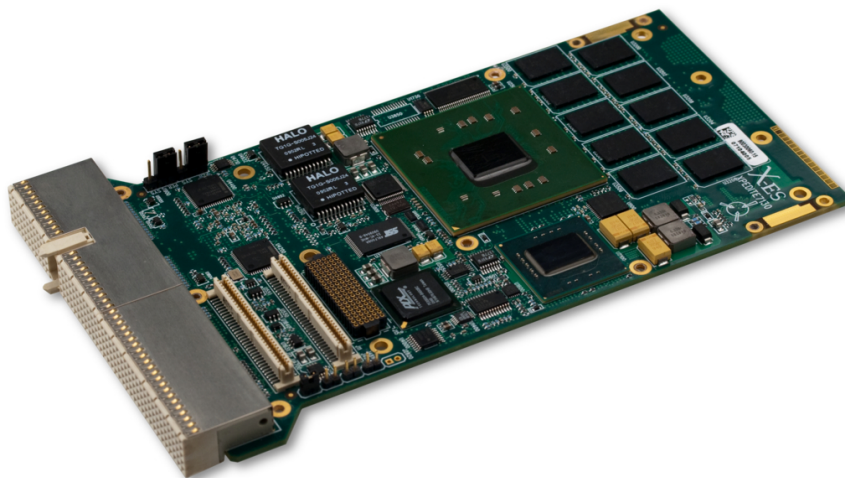
XPedite7130

End Of Life

Intel® Core™2 Duo Processor-Based Conduction- or Air-Cooled 3U cPCI Module

Please use [XPedite7431](#)

- › Intel® Core™2 Duo processor at up to 1.8 GHz
- › 3U cPCI module
- › Conduction or air cooling
- › Up to 4 GB of DDR2-400 ECC SDRAM
- › Up to 2 MB firmware hub flash (or 1 MB with redundancy)
- › 4 GB of NAND flash
- › XMC/PrPMC interface with front panel I/O support
- › 32-bit, 33 MHz cPCI rear panel interface
- › Two rear panel Gigabit Ethernet ports with integrated magnetics
- › Two rear panel USB 2.0 high-speed ports
- › Six rear panel SATA 1.5 Gb/s ports
- › Two rear panel RS-232/422/485 serial ports
- › Front I/O available via plugover module
- › Linux BSP
- › Wind River VxWorks BSP
- › QNX Neutrino BSP
- › Green Hills INTEGRITY BSP
- › Microsoft Windows drivers



XPedite7130

The XPedite7130 is a high-performance, low-power 3U cPCI single board computer based on the Intel® Core™2 Duo processor. With two Gigabit Ethernet ports and a 33 MHz PCI interface, the XPedite7130 is ideal for high-bandwidth data-processing applications.

The XPedite7130 accommodates up to 4 GB of DDR2-400 ECC SDRAM to support memory-intensive applications, and hosts numerous I/O ports including Gigabit Ethernet, USB 2.0, SATA 1.5 Gb/s, and RS-232/422/485 through the P2 backplane connector.

Linux 2.6, Wind River VxWorks, QNX Neutrino, and Green Hills INTEGRITY Board Support Packages (BSPs), as well as Microsoft Windows drivers, are available for the XPedite7130.

X-ES

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...Always Fast

Extreme Engineering Solutions

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Processor

- Intel® Core™2 Duo at up to 1.8 GHz
- 200 MHz (800 MT/s) FSB
- Up to 6 MB of L2 cache

Memory

- Up to 4 GB of DDR2-400 ECC SDRAM
- Up to 2 MB firmware hub flash (or 1 MB with redundancy)
- 4 GB of NAND flash

J1 cPCI

- 32-bit, 33/66 MHz PCI interface
- System controller capable with onboard clocking and arbitration
- Peripheral slot capable

J2 cPCI Interface

- Two Gigabit Ethernet ports
- Six SATA 1.5 Gb/s ports
- Two USB 2.0 ports
- Two RS-232/422/485 serial ports
- I²C port
- 3.3 V GPIO signals

PrPMC/XMC Site

- 32-bit, 33 MHz PCI bus (PMC interface)
- x4 PCIe port (XMC interface)

Front Panel I/O

- Front panel RJ-45 Ethernet, USB, and micro-DB-9 RS-232 serial ports available via optional plugover module

Software Support

- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP
- Green Hills INTEGRITY BSP
- Microsoft Windows drivers

Physical Characteristics

- 3U cPCI conduction- or air-cooled form factor
- Dimensions: 100 mm x 160 mm
- 0.8 in. pitch

Environmental Requirements

- Contact factory for appropriate board configuration based on environmental requirements.
- Supported ruggedization levels (see chart below): 1, 3, 5
 - Conformal coating available as an ordering option

Power Requirements

- Power will vary based on configuration and usage. Please consult factory.

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C ambient
Vibration	0.002 g ² /Hz, 5 to 2000 Hz	0.04 g ² /Hz (maximum), 5 to 2000 Hz	0.1 g ² /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

